

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Agarwal et al.

Application No. 09/590,795

Filed: June 8, 2000

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING RUTHENIUM AND TUNGSTEN
CONTAINING LAYERS

Examiner: Cuong Q. Nguyen


Date: July 19, 2001



Art Unit: 2811

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on July 19, 2001 as First Class Mail in an envelope addressed to: BOX NON-FEE AMENDMENT COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.


Attorney for Applicant

#4
Election
F. JONES
7-30-01

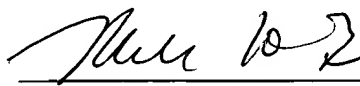
BOX NON-FEE AMENDMENT
COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

RESPONSE TO OFFICE ACTION

In response to the Office Action of June 20, 2001, Applicants elect Claims 1-50 and 60-70 (Group II) for examination.

Respectfully submitted,

KLARQUIST SPARKMAN CAMPBELL
LEIGH & WHINSTON, LLP

By 
Michael D. Jones
Registration No. 41,879

One World Trade Center, Suite 1600
121 S.W. Salmon Street
Portland, Oregon 97204
Telephone: (503) 226-7391
Facsimile: (503) 228-9446

RECEIVED
JUL 27 2001
TECHNOLOGY CENTER 2800